



## Material Content Data Sheet



<b>Sales Product Name</b>		ESD103-B1-02ELS E6327		<b>Issued</b>		22. January 2018		
<b>MA#</b>		MA001248188						
<b>Package</b>		PG-TSSLP-2-4		<b>Weight*</b>		0.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.17		1667	
	noble metal	gold	7440-57-5	0.001	0.65		6459	
	inorganic material	silicon	7440-21-3	0.010	4.79	5.61	47874	56000
leadframe	non noble metal	nickel	7440-02-0	0.108	51.63	51.63	516380	516380
wire	noble metal	gold	7440-57-5	0.003	1.32	1.32	13195	13195
encapsulation	organic material	carbon black	1333-86-4	0.000	0.19		1887	
	plastics	epoxy resin	-	0.011	5.47		54686	
	inorganic material	silicondioxide	60676-86-0	0.067	32.06	37.72	320584	377157
leadfinish	noble metal	gold	7440-57-5	0.004	1.76	1.76	17619	17619
plating	noble metal	gold	7440-57-5	0.004	1.96	1.96	19649	19649
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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